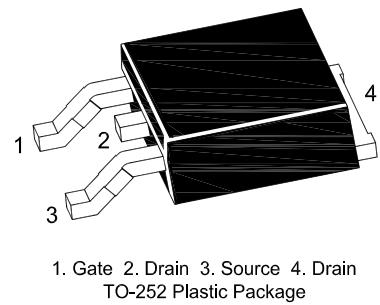
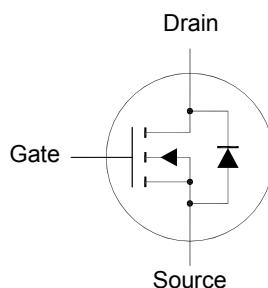


SFTN9980R-HAF

N-Channel Enhancement Mode MOSFET

Features

- Halogen and Antimony Free(HAF), RoHS compliant



1. Gate 2. Drain 3. Source 4. Drain
TO-252 Plastic Package

Absolute Maximum Ratings($T_a = 25^\circ\text{C}$)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V_{DS}	80	V
Gate-Source Voltage	V_{GS}	± 25	V
Drain Current $T_C = 25^\circ\text{C}$ $T_C = 100^\circ\text{C}$	I_D	21.3 13.4	A
Peak Drain Current ¹⁾	I_{DM}	80	A
Power Dissipation $T_C = 25^\circ\text{C}$	P_D	41.7	W
Operating Junction and Storage Temperature Range	T_J, T_{stg}	- 55 to + 150	°C

Thermal Resistance Ratings

Parameter	Symbol	Max.	Unit
Thermal Resistance from Junction to Ambient ²⁾	$R_{\theta JA}$	62.5	°C/W
Maximum Thermal Resistance from Junction to Case	$R_{\theta JC}$	3	°C/W

¹⁾ Pulse width limited by Max. junction temperature.

²⁾ Surface mounted on 1 in² copper pad of FR4 board.

TOP DYNAMIC



Dated: 02/09/2016 Rev: 01

SFTN9980R-HAF

Characteristics at $T_a = 25^\circ\text{C}$ unless otherwise specified

Parameter	Symbol	Min.	Typ.	Max.	Unit
Drain-Source Breakdown Voltage at $I_D = 250 \mu\text{A}$	$V_{(\text{BR})\text{DSS}}$	80	-	-	V
Zero Gate Voltage Drain Current at $V_{DS} = 80 \text{ V}$ at $V_{DS} = 64 \text{ V}, T_J = 125^\circ\text{C}$	I_{DSS}	- -	- -	10 100	μA
Gate-Source Leakage at $V_{GS} = \pm 25 \text{ V}$	I_{GSS}	-	-	± 100	nA
Gate-Source Threshold Voltage at $V_{DS} = V_{GS}, I_D = 250 \mu\text{A}$	$V_{GS(\text{th})}$	1	-	3	V
Drain-Source On-State Resistance at $V_{GS} = 10 \text{ V}, I_D = 12 \text{ A}$ at $V_{GS} = 4.5 \text{ V}, I_D = 8 \text{ A}$	$R_{DS(\text{on})}$	- -	- -	45 55	$\text{m}\Omega$
Forward Transconductance at $V_{DS} = 10 \text{ V}, I_D = 12 \text{ A}$	$ g_{FS} $	-	20	-	S
Input Capacitance at $V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$	C_{iss}	-	-	2900	pF
Output Capacitance at $V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$	C_{oss}	-	135	-	pF
Reverse Transfer Capacitance at $V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$	C_{rss}	-	96	-	pF
Turn-On Delay Time at $V_{DS} = 40 \text{ V}, I_D = 12 \text{ A}, V_{GS} = 10 \text{ V}, R_G = 3.3 \Omega$	$t_{d(on)}$	-	11	-	ns
Turn-On Rise Time at $V_{DS} = 40 \text{ V}, I_D = 12 \text{ A}, V_{GS} = 10 \text{ V}, R_G = 3.3 \Omega$	t_r	-	20	-	ns
Turn-Off Delay Time at $V_{DS} = 40 \text{ V}, I_D = 12 \text{ A}, V_{GS} = 10 \text{ V}, R_G = 3.3 \Omega$	$t_{d(off)}$	-	29	-	ns
Turn-Off Fall Time at $V_{DS} = 40 \text{ V}, I_D = 12 \text{ A}, V_{GS} = 10 \text{ V}, R_G = 3.3 \Omega$	t_f	-	30	-	ns

Drain-Source Body Diode Rating Characteristics

Parameter	Symbol	Max.	Unit
Drain-Source Diode Forward Voltage ¹⁾ at $I_S = 20 \text{ A}$	V_{SD}	1.2	V

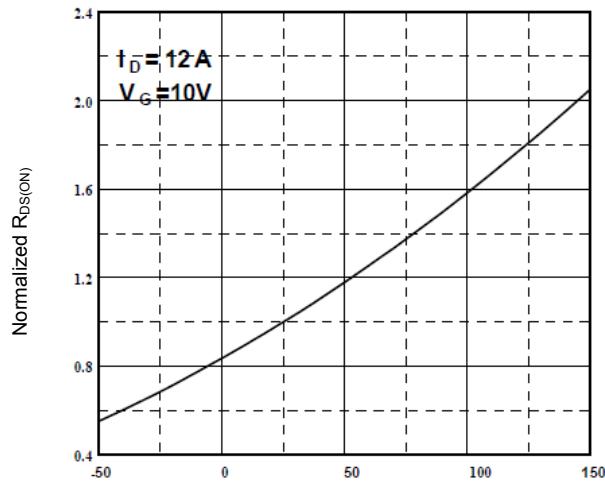
¹⁾ Pulse Test

TOP DYNAMIC

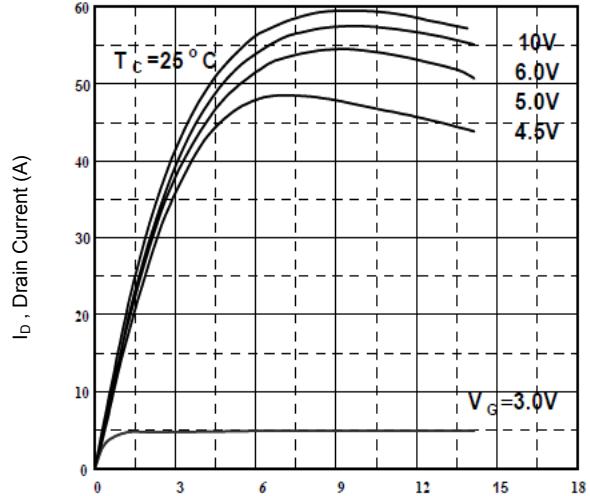


Dated: 02/09/2016 Rev: 01

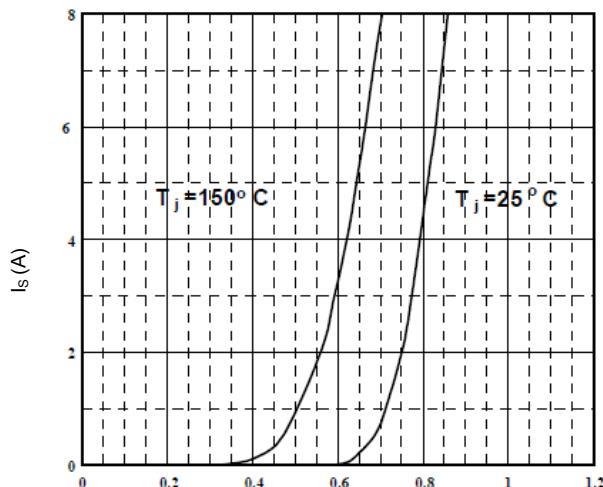
SFTN9980R-HAF



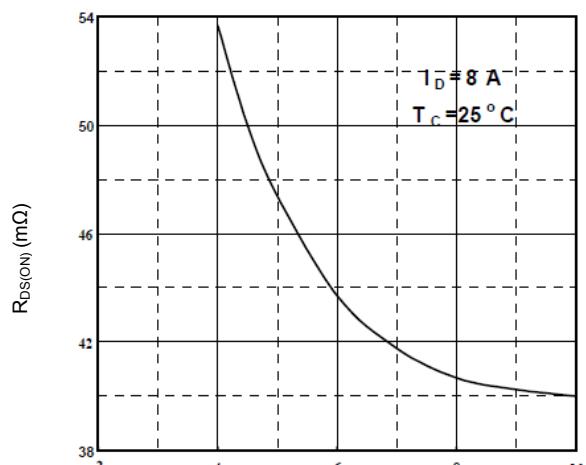
T_J , Junction Temperature (°C)
Figure 1. Normalized On Resistance v.s. Junction Temperature



V_{DS} , Drain to Source Voltage (V)
Figure 2.Typical Output Characteristics



V_{SD} , Source to Drain Voltage (V)
Figure 3. Forward Characteristic of Reverse Diode



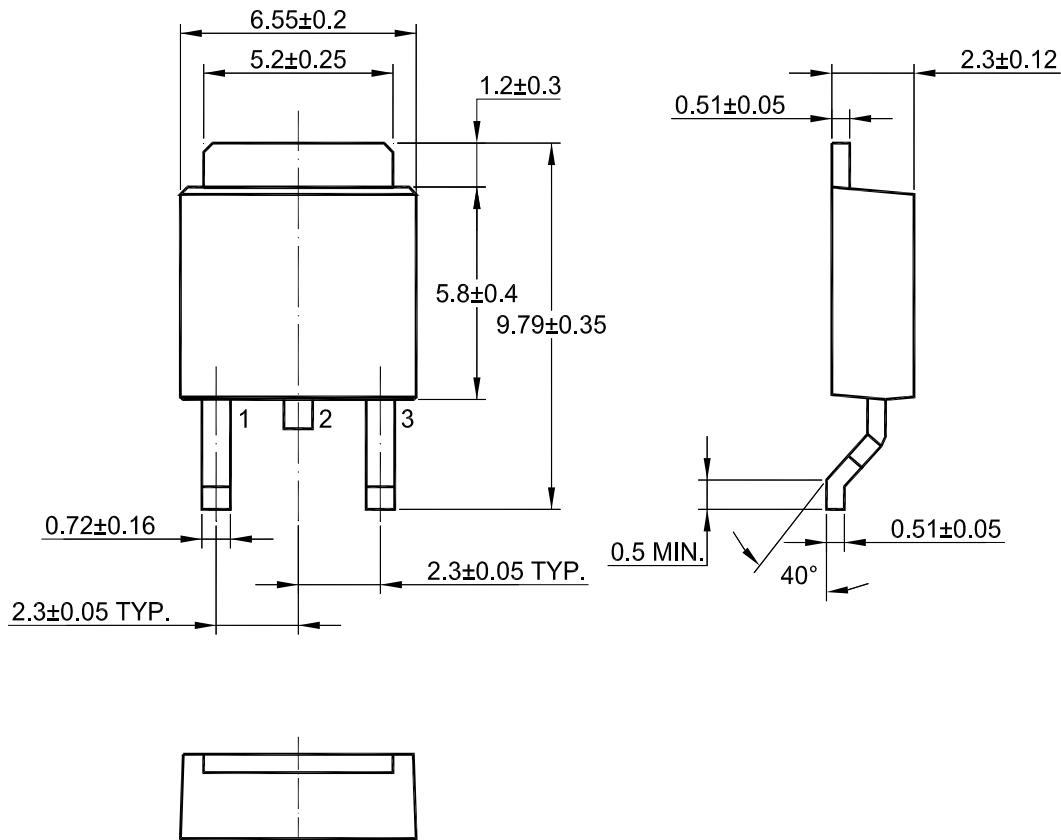
V_{GS} , Gate to Source Voltage (V)
Figure 4.On Resistance v.s. Gate Voltage

TOP DYNAMIC



Dated: 02/09/2016 Rev: 01

TO-252 PACKAGE OUTLINE



Dimensions in mm

TOP DYNAMIC

